



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE82452-3SA			<b>Issued</b>	25. September 2017			
<b>MA#</b>	MA001272112							
<b>Package</b>	PG-DSO-36-54			<b>Weight*</b>	2107.55 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	21.749	1.03	1.03	10320	10320
leadframe	inorganic material	phosphorus	7723-14-0	0.388	0.02		184	
	non noble metal	zinc	7440-66-6	1.553	0.07		737	
	non noble metal	iron	7439-89-6	31.066	1.47		14740	
wire	non noble metal	copper	7440-50-8	1261.410	59.87	61.43	598521	614182
	non noble metal	copper	7440-50-8	2.591	0.12	0.12	1229	1229
	encapsulation	organic material	carbon black	1333-86-4	1.517	0.07		720
	plastics	epoxy resin	-	69.774	3.31		33107	
	inorganic material	silicondioxide	60676-86-0	687.125	32.60	35.98	326030	359857
leadfinish	non noble metal	tin	7440-31-5	15.044	0.71	0.71	7138	7138
plating	noble metal	silver	7440-22-4	0.644	0.03	0.03	305	305
solder	noble metal	silver	7440-22-4	0.220	0.01		105	
	non noble metal	tin	7440-31-5	0.147	0.01		70	
	non noble metal	lead	7439-92-1	14.318	0.68	0.70	6794	6969
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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